



Product Manual

EKWIN ELECTRONICS CO.,LTD

EK 65NF06

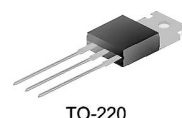
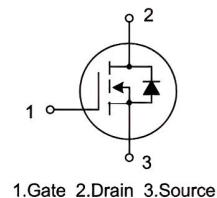
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EK65NF06

N-CHANNEL MOSFET

Product Summary :

T _{TYPE}	V _{DSS}	R _{DS(on)} Typ.	I _D
65NF06	60V	8.5mΩ	65A



Features :

- 60V/65A
- Lead free and Green Device Available
- Low Rds-on to Minimize Conductive Loss
- High avalanche Current

General Description :

EK60NF06 is an N channel enhancement mode power MOS field effect transistor which is produced by EKWIN. The advanced trench technology and the improved guard ring terminal have been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

Application :

- ❖ Power Supply
- ❖ UPS
- ❖ Battery Management System

Electrical Characteristics($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Characteristics	Test conditions	Min	Typ	Max	Unit
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	2.0	3.0	4.0	V
$R_{DS(on)}$	Static Drain- Source On State Resistance	$V_{GS}=10\text{V}, I_D=10\text{A}$	-	8.5	15	m Ω
B_{VDS}	Drain -Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60	-	-	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=48\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 25\text{V}, V_{DS}=0\text{V}$	-	-	± 100	nA
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V}$ $f=1.0\text{MHz}$	-	3000	-	pF
C_{oss}	Output Capacitance		-	170	-	
C_{rss}	Reverse Transfer Capacitance		-	140	-	
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30\text{V}, I_D=30\text{A}$ $R_G=3\Omega$ (Note2,3)	-	49	-	ns
t_r	Turn-on Rise Time		-	230	-	
$t_{d(off)}$	Turn-off Delay Time		-	65	-	
t_f	Turn-off Fall Time		-	110	-	
Q_g	Total Gate Charge	$V_{DS}=48\text{V}, I_D=30\text{A}$ $V_{GS}=10\text{V}$ (Note2,3)	-	56	-	nC
Q_{gs}	Gate-Source Charge		-	16	-	
Q_{gd}	Gate-Drain Charge		-	18	-	

Thermal Characteristics

Symbol	Characteristics	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.7	$^{\circ}\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	$^{\circ}\text{C/W}$

Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Characteristics		Maximum		Unit
VDSS	Drain-Source Voltage		60		V
VGSS	Gate-Source Voltage		±20		V
ID	Drain Curren	TC=25°C	65		A
		TC=100°C	50		
IDP	Pulsed Drain Current (TC=25°C)		250		A
PD	Power Dissipation(TC=25°C)		Tc=25°C	88	W
	Derate above 25°C		TC=100°C	44	W/°C
EAS	Single Pulsed Avalanche Energy		240		mJ
TJ	Operation Junction Temperature Range		-55~+175		°C
Tstg	Storage Temperature Range		-55~+175		°C

Notes:

1. Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 2: Guaranteed by design, not subject to production testing.
- 3: Package limitation current is 50A.Calculated continuous current based on maximum allowable junction temperature.
- 4: Repetitive rating, pulse width limited by max junction temperature.
- 5: Starting TJ = 25°C,L = 0.5mH,IAS = 31A.

Typical Characteristics

Figure 1 Output characteristics

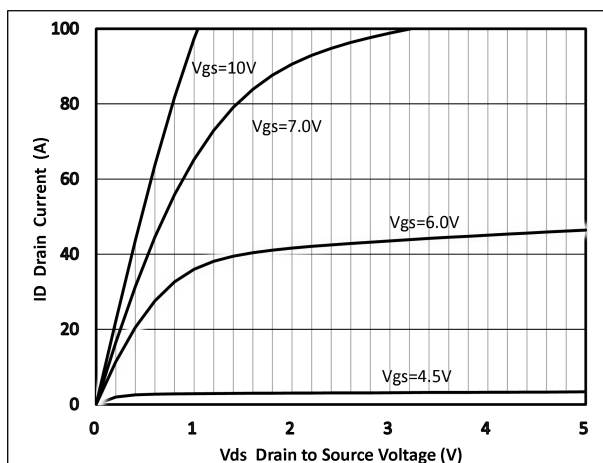


Figure 2 Transfer Characteristics

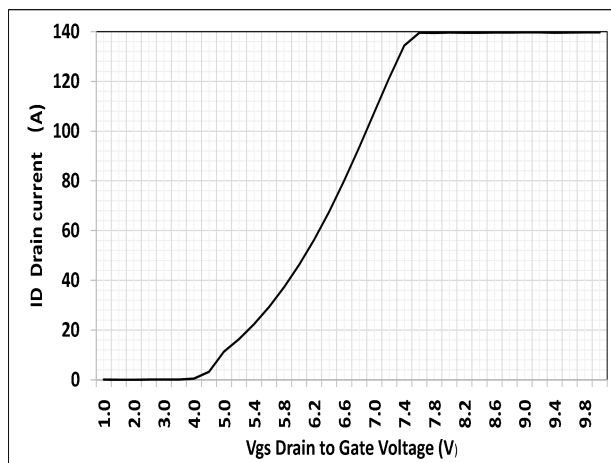


Figure 3 On-Resistance vs Id

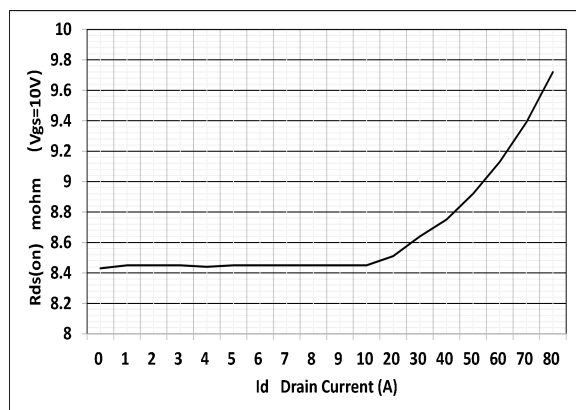


Figure 4 On-Resistance vs Vgs

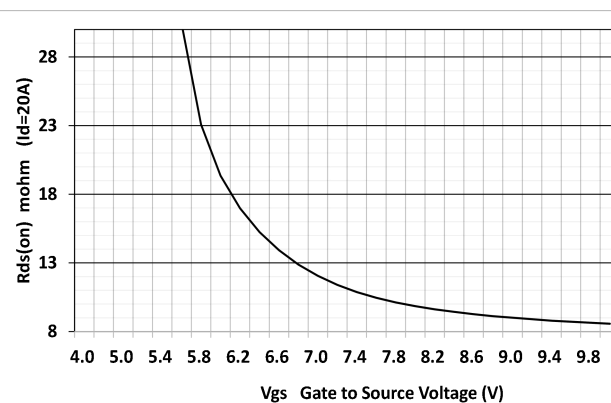


Figure 5 Body Diode Forward Voltage

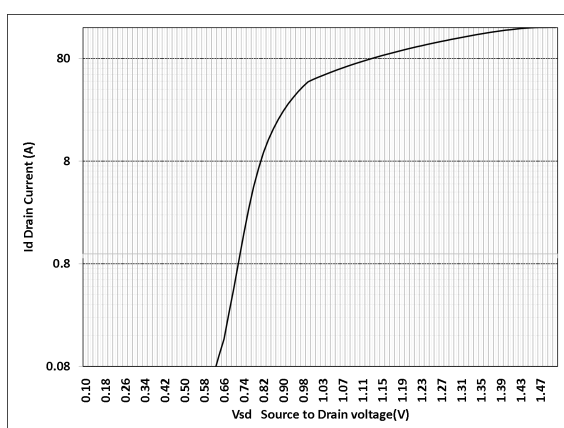
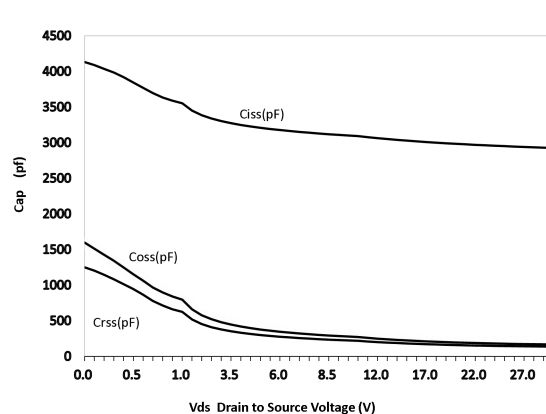
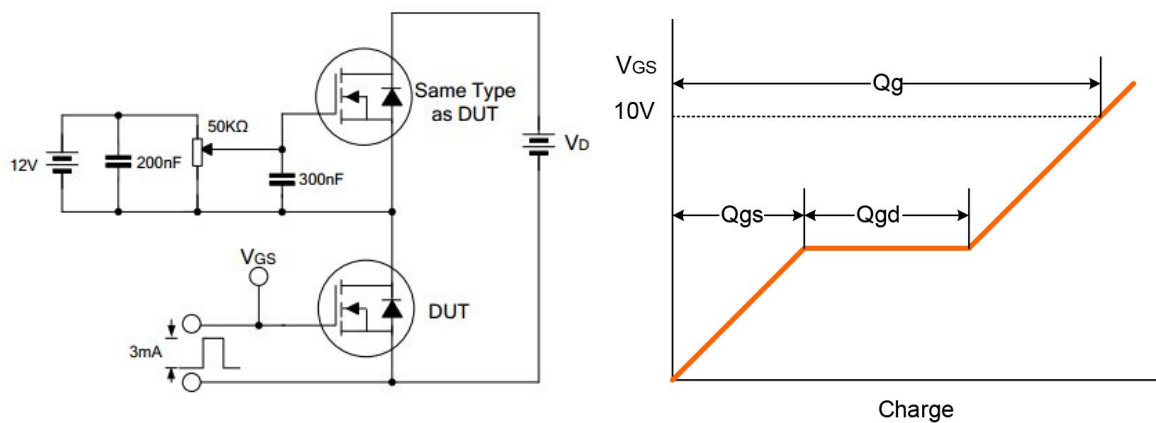


Figure 6 Capacitance Characteristics

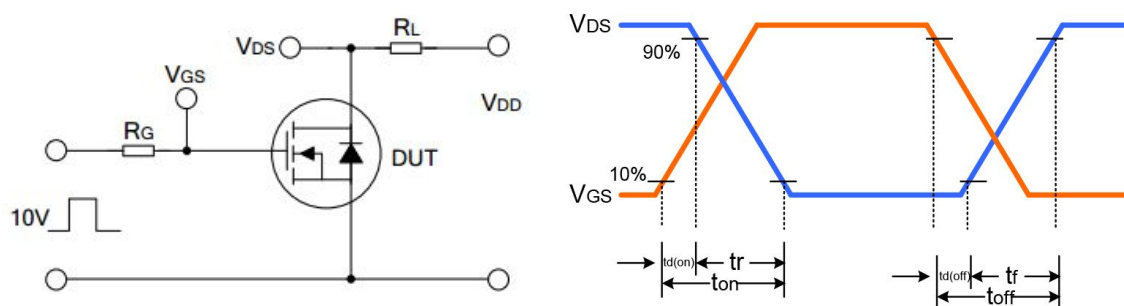


Typical Test Circuit

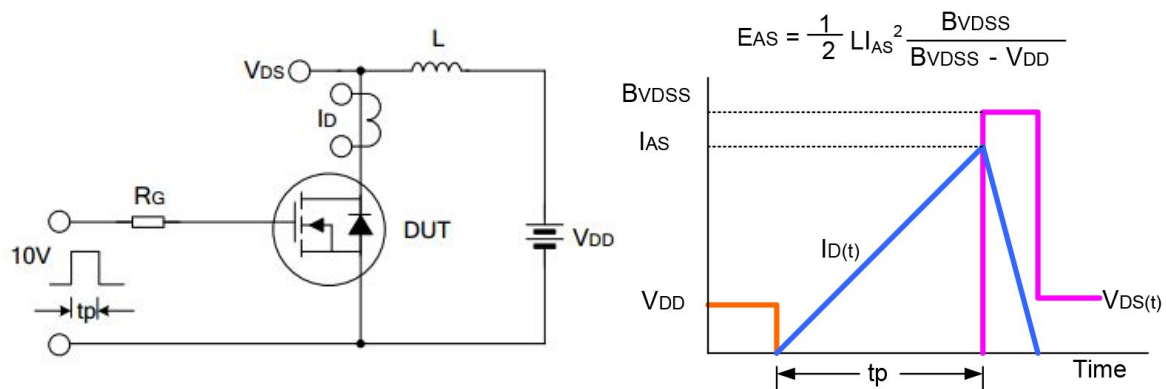
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching Test Circuit & Waveform



Package Outline

TO-220

